



Product Change Notification

Change Notification #: 826056-00

**Change Title: MINOR CHANGE,
Country of Wafer Level Assembly,
PCN 826056-00, Transport Media, Label,
Interpretation of COO for Foveros Single Stack IC
Products**

Date of Publication: July 22, 2024

Key Characteristics of the Change:

Transport Media, Label

Forecasted Key Milestones:

| | |
|--|------------------|
| Date Customer Must be Ready to Receive Post-Conversion Material | October 08, 2024 |
|--|------------------|

Description of Change to the Customer:

Intel is updating its Country of Origin (COO) determination values for Foveros Single Stacked Integrated Circuits (SSICs) on labels. Foveros SSICs are modular manufactured Integrated Circuits, where multiple die (i.e., chiplets) are combined (“stacked”) to create a single “unit” at a stage of manufacturing called Wafer Level Assembly.

A finished product SSIC contains only one such stacked “unit” as opposed to below examples, which are outside of the scope of this change notification:

- a monolithic IC (contains a single die); or
- multi-die, non-modular manufactured IC; or
- multi-stacked IC (contains 2 or more stacked “units”, with or without other die in the final assembly).

For Foveros SSIC products, the label header and interpreted value changes which customers will see on labels are similar to the changes previously communicated in [PCN 813836-01](#) hyper-linked herein.

As communicated previously per PCN 813836-01, on various labels used in the shipment of products, Intel is replacing the reference to Country of Origin (COO) with two new label headers entitled, “*Manufactured In*” and “*Final Assembly*” with their accompanying value(s).

This communication herein is to inform customers particularly that for Intel’s Foveros SSICs, when products are shipped into the United States, the COO value that will display on Shipping Labels and Intermediate Box Labels will come from the Country of Wafer Level Assembly (COW). Barcoded values (where applicable) will depend upon the location and product. Please see the chart below.

Please note that “*Manufactured In*” on the shipping labels will reflect COW values (multiple whenever applicable). Due to system limitations, whenever applicable, the default COO on a label barcode for the Foveros SSIC products would feature a single value of COW.

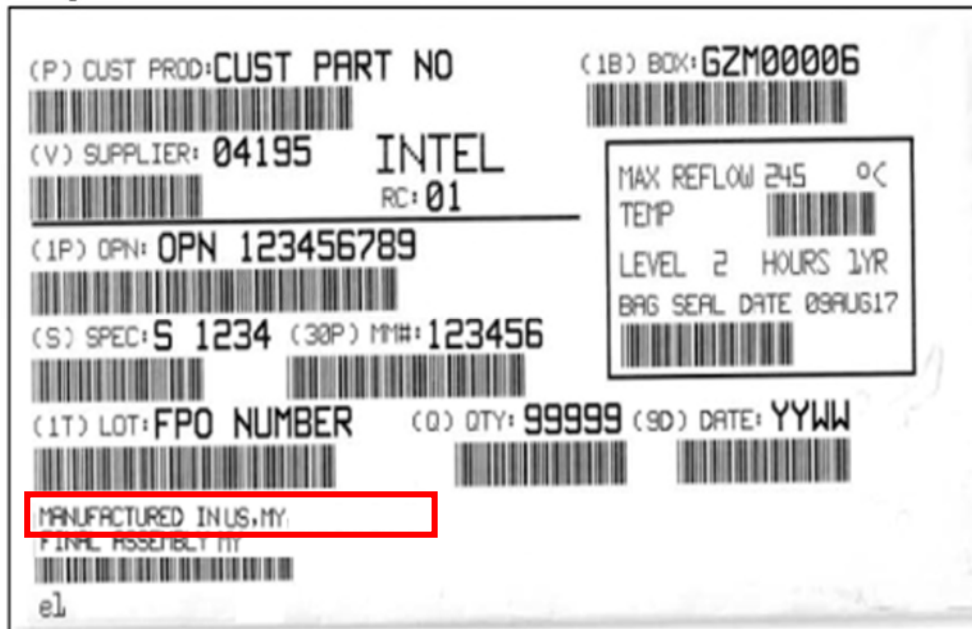
Interpretation of COO for Foveros Single Stack IC Products*

| | Label Header & Value | Ship to US | Ship to Japan | Ship to Others (non-US/non-Japan) |
|----------------|---|------------|---------------|-----------------------------------|
| Shipping Label | Manufactured in COW Final Assembly COA | COO = COW | COO = COF | COO = COA |
| IBox Label | Manufactured in COW Final Assembly COA | COO = COW | COO = COF | COO = COA |

*Also applies to Barcoded Field/Values

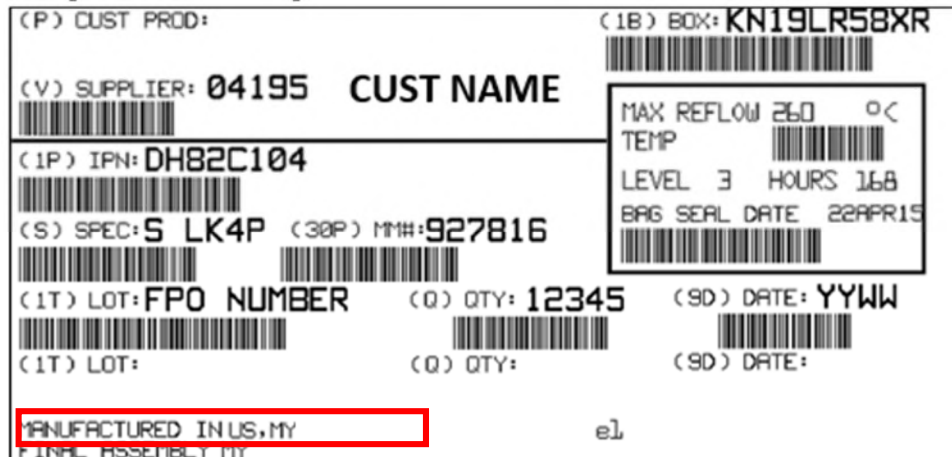
Please be aware that pictures shared below are for example purposes only and represent a change being applied broadly to hundreds of labels that may have the “Manufactured In” label header applied. They do not represent every label Intel places on shipments.

Example of a Standard Intermediate Box Label



Note: Barcode contains the Country of Origin (COO) value = Country of Wafer Level Assembly (COW). See interpretation table above.

Example of a Customer Specific Intermediate Box Label



Note: If customers have a unique label showing their customer name in the label, the word “Intel” would be replaced with the customer’s name.

Example of Standard Shipping Label

| | |
|--------------------------------|----------------|
| FROM: | TO: |
| <hr/> | |
| (3S) PKG ID: 4195+081090 | |
| | |
| (K) PO NUMBER: 13728 | |
| | |
| (P) CUSTOMER PROD ID: 30021 | |
| | |
| (Q) QTY: 28 EA (1P) H#:#: 99A0 | |
| | |
| Manufactured in US | |
| Final Assembly H# | |
| | |
| (1B) BOX ID: KN2C | |
| | |
| (1T) FPO NO: L331E3 | (S0) D/C: 2331 |
| | |
| INTEGRATED CIRCUITS | |
| PACKAGE WEIGHT: | |
| 11.60 LBS | |
| 5.26 KGS | |
| PACKAGE COUNT: | |
| 1 OF 80 | |

Note: *Manufactured In* on the shipping labels will now reflect COW (Country of Wafer Level Assembly) value (multiple whenever applicable) = US in this example. **Barcode COO Value** will default to single value highest count of COW.

Customer Impact of Change and Recommended Action:

Intel considers this a Minor Change. This value interpretation for the Country of Wafer Level Assembly (COW) pertains only to labels printed for Foveros Single Stacked Integrated Circuits (SSICs). The change is not for the finished good products. There is no change to the form, fit, functionality, quality or reliability of finished good products.

Customers should expect to see a mixture of shipments using older labels and newly changed labels until the older label stock inventory is fully depleted. Any existing label stock/materials labeled previously and packed and/or stored already as warehouse inventory will not be relabeled before shipping to customers.

This change is not expected to be a quick change. The process will start October 8, 2024 and is anticipated to take several quarters to implement across all labels impacted by the scope.

Customers should notify their inbound shipment & receiving departments to expect and anticipate these label changes.

Distributors should forward this communication to their customers accordingly.

Please contact your appropriate Intel Account Representative with any questions or concerns regarding the changes communicated in this updated Product Change Notification.

Products Affected/Intel Ordering Codes:

This change is not product specific. The changes communicated herein apply to Foveros SSICs' labels where the translation value of Country of Origin (COO) is determined. Therefore, no product list is available.

PCN Revision History:

| Date of Revision: | Revision Number: | Reason: |
|--------------------------|-------------------------|--------------------------|
| July 22, 2024 | 00 | Originally Published PCN |



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826056-00

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No response from customers will be deemed an acceptance of the change, and the change will be implemented pursuant to the key milestones set forth in this attached PCN.

Should you have any issues with the timeline or content of this change, please contact the Intel Representative(s) for your geographic location listed below.

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